L Number	Hits	Search Text	DB	Time stamp
1	728157	mold	USPAT;	2003/08/27 13:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	396578	photolithograph\$6 photoresist photosensitive	USPAT;	2003/08/27 13:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	318129	spacer	USPAT;	2003/08/27 13:15
		•	US-PGPUB;	, ,
		•	EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	30639	349\$.ccls.	USPAT;	2003/08/27 13:15
			US-PGPUB;	
			EPO; JPO;	i
			DERWENT;	
			IBM TDB	
4	12	mold near10 (photolithograph\$6 photoresist	USPAT;	2003/08/27 13:18
		photosensitive) near10 spacer	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		•	IBM TDB	
6	58	mold same (photolithograph\$6 photoresist	USPAT;	2003/08/27 13:18
		photosensitive) same spacer	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	4	349\$.ccls. and (mold same (photolithograph\$6	USPAT;	2003/08/27 13:19
		photoresist photosensitive) same spacer)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	46	, , = 1	USPAT;	2003/08/27 13:19
		photosensitive) same spacer) not (mold	US-PGPUB;	
		near10 (photolithograph\$6 photoresist	EPO; JPO;	
		photosensitive) near10 spacer)	DERWENT;	
			IBM_TDB	

L Number	Hits	Search Text	DB	Time stamp
1	1383	(349/155,156).ccls.	USPAT;	2003/08/27 11:08
-	1303	(0.10), 1.00), 1.00=1	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	
2	1091	(264/61,129,272.1).ccls.	USPAT;	2003/08/27 11:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0.00		IBM_TDB	0000/00/05 11 00
3	2681	438/624.ccls.	USPAT;	2003/08/27 11:09
]		,	US-PGPUB; EPO; JPO;	
		,	DERWENT;	
			IBM TDB	
4	1432	445/24.ccls.	USPAT;	2003/08/27 11:09
*	1432	145/24.0015.	US-PGPUB;	2003/00/2/ 11:03
			EPO; JPO;	
		,	DERWENT;	
			IBM TDB	
5	513	(216/25,33).ccls.	USPAT;	2003/08/27 11:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	1551	(427/77,105,106,133).ccls.	USPAT;	2003/08/27 11:09
		,	US-PGPUB;	
	·		EPO; JPO;	
		·	DERWENT;	
		(IBM_TDB	2002/00/27 11 10
7	6669	(primary positive) near5 mold	USPAT;	2003/08/27 11:10
1			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	119676	photoresist	USPAT;	2003/08/27 11:10
		•	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	343373	spacer (dielectric adj (sturcture film))	USPAT;	2003/08/27 11:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
11	0	(spacer (dielectric adj (sturcture film)))	IBM_TDB USPAT;	2003/08/27 11:12
**		same (((primary positive) near5 mold) same	US-PGPUB;	2003,00/2/ 11:12
		photoresist)	EPO; JPO;	
		× · · · · · · · · · · · · · · · · · · ·	DERWENT;	
			IBM TDB	
12	0	((349/155,156).ccls.) and (((primary	USPAT;	2003/08/27 11:12
		positive) near5 mold) same photoresist)	US-PGPUB;	
		_	EPO; JPO;	
			DERWENT;	
			IBM_TDB	, ,
13	0		USPAT;	2003/08/27 11:12
		positive) near5 mold) same photoresist)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
14	0	138/634 cala and ///nrimary nacitive\	IBM_TDB USPAT;	2003/08/27 11:12
1 - 3		438/624.ccls. and (((primary positive) near5 mold) same photoresist)	US-PGPUB;	2003/00/2/ 11:12
		licars mora, same buocoresisci	EPO; JPO;	
	1		DERWENT;	
]		IBM TDB	
15	0	445/24.ccls. and (((primary positive) near5	USPAT;	2003/08/27 11:12
1	1	mold) same photoresist)	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
1			IBM_TDB	

17	0	((427/77,105,106,133).ccls.) and (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB;	2003/08/27 11:12
			EPO; JPO; DERWENT;	
16	1		IBM_TDB USPAT;	2003/08/27 11:12
		near5 mold) same photoresist)	US-PGPUB; EPO; JPO; DERWENT;	
18	2	and (((primary positive) near5 mold) same	IBM_TDB USPAT; US-PGPUB;	2003/08/27 11:13
		photoresist)	EPO; JPO; DERWENT; IBM TDB	
10	31	((primary positive) near5 mold) same photoresist	USPAT; US-PGPUB; EPO; JPO;	2003/08/27 11:16
	85551	photolithograph\$5	DERWENT; IBM_TDB USPAT;	2003/08/27 11:16
17			US-PGPUB; EPO; JPO; DERWENT;	
20	6	((primary positive) near5 mold) near10 photolithograph\$5	IBM_TDB USPAT; US-PGPUB;	2003/08/27 11:17
		Feeders	EPO; JPO; DERWENT; IBM TDB	
21	0	<pre>((primary positive) near5 mold) same photolithograph\$5 same (spacer (dielectric adj (sturcture film)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/27 11:18
22	9	((primary positive) near5 mold) same photolithograph\$5	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/08/27 11:18
23	3	(((primary positive) near5 mold) same photolithograph\$5) not (((primary positive) near5 mold) near10 photolithograph\$5)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/08/27 11:18
24	1091		DERWENT; IBM_TDB USPAT;	2003/08/27 11:19
			US-PGPUB; EPO; JPO; DERWENT;	
25	14	((primary positive) near5 mold) and 264/129.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/08/27 11:20
26	0	((349/155,156).ccls.) and ((primary	DERWENT; IBM_TDB USPAT;	2003/08/27 11:20
		positive) near5 mold)	US-PGPUB; EPO; JPO; DERWENT;	,,
27	48	<pre>(spacer (dielectric adj (sturcture film))) same ((primary positive) near5 mold)</pre>	IBM_TDB USPAT; US-PGPUB;	2003/08/27 11:20
			EPO; JPO; DERWENT; IBM_TDB	